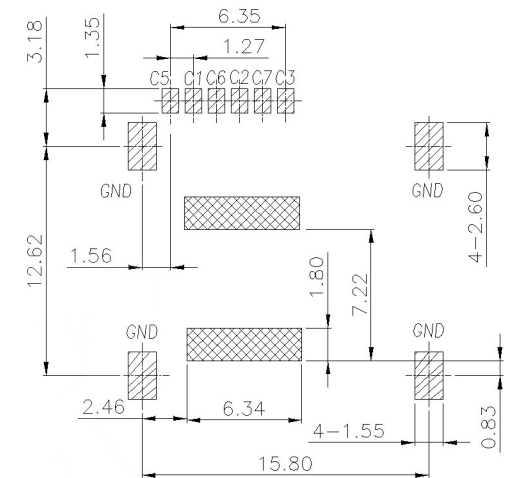
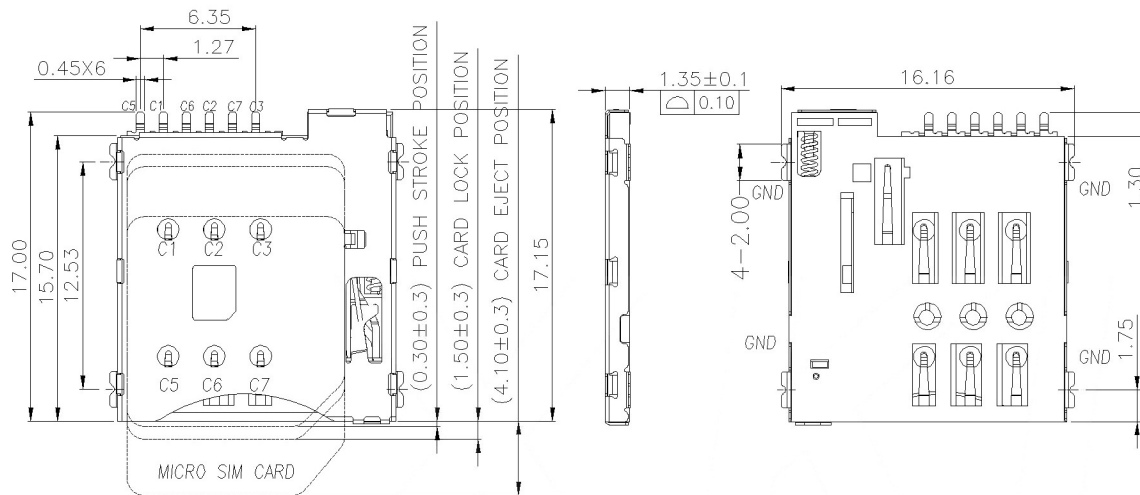


3FF SIM CARD

FORBIDDEN AREA
SMT SOLDER AREA
THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

NOTES:

1) MATERIAL:

HOUSING: HI-TEMP. PLASIC UL 94V-0

TERMINAL: COPPER ALLOY

SHELL: SUS

2) FINISH:

CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,

ITEM	PAPT NAMF	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP. PLASIC UL 94V-0	BLACK

MARK	DESCRIPTION	REVISIONS	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DSND	DATE	SCALE: N/A	MODEL TYPE: SIM CARD CONN
Δ X						ANGLAR				PART NO.:
Δ X						$L \leq 4$			VIEW:	
Δ X						$4 < L \leq 16$			UNIT: mm	DWG NO.:
						$16 < L \leq 63$			SIZE: A4	XKSIM-114
						$L > 63$				WEIGHT
										1.0g
										SHEET
										1/1
										REVISION
										A0

Kosod Technology Co., Ltd.